

74AVCH2T45

**Dual-bit, dual-supply voltage level translator/transceiver;
3-state**

Rev. 9.1 — 12 August 2024

Product data sheet

1. General description

The 74AVCH2T45 is a dual bit, dual supply transceiver that enables bidirectional level translation. It features two data input-output ports (nA and nB), a direction control input (DIR) and dual supply pins ($V_{CC(A)}$ and $V_{CC(B)}$). Both $V_{CC(A)}$ and $V_{CC(B)}$ can be supplied at any voltage between 0.8 V and 3.6 V making the device suitable for translating between any of the low voltage nodes (0.8 V, 1.2 V, 1.5 V, 1.8 V, 2.5 V and 3.3 V). Pins nA and DIR are referenced to $V_{CC(A)}$ and pins nB are referenced to $V_{CC(B)}$. A HIGH on DIR allows transmission from nA to nB and a LOW on DIR allows transmission from nB to nA.

The device is fully specified for partial power-down applications using I_{OFF} . The I_{OFF} circuitry disables the output, preventing any damaging backflow current through the device when it is powered down. In suspend mode when either $V_{CC(A)}$ or $V_{CC(B)}$ are at GND level, both A and B are in the high-impedance OFF-state.

The 74AVCH2T45 has active bus hold circuitry which is provided to hold unused or floating data inputs at a valid logic level. This feature eliminates the need for external pull-up or pull-down resistors.

2. Features and benefits

- Wide supply voltage range: 0.8 V to 3.6 V for $V_{CC(A)}$ and $V_{CC(B)}$
- High noise immunity
- Suspend mode
- Bus hold on data inputs
- Inputs accept voltages up to 3.6 V
- Low noise overshoot and undershoot < 10 % of V_{CC}
- I_{OFF} circuitry provides partial Power-down mode operation
- Maximum data rates:
 - 500 Mbps (1.8 V to 3.3 V translation)
 - 320 Mbps (< 1.8 V to 3.3 V translation)
 - 320 Mbps (translate to 2.5 V or 1.8 V)
 - 280 Mbps (translate to 1.5 V)
 - 240 Mbps (translate to 1.2 V)
- Latch-up performance exceeds 100 mA per JESD 78 Class II
- Complies with JEDEC standards:
 - JESD8-12 (0.8 V to 1.3 V)
 - JESD8-11 (0.9 V to 1.65 V)
 - JESD8-7 (1.2 V to 1.95 V)
 - JESD8-5 (1.8 V to 2.7 V)
 - JESD8-B (2.7 V to 3.6 V)
- ESD protection:
 - HBM: ANSI/ESDA/JEDEC JS-001 class 3B exceeds 8000 V
 - CDM: ANSI/ESDA/JEDEC JS-002 class C3 exceeds 1000 V
- Multiple package options
- Specified from -40 °C to +85 °C and -40 °C to +125 °C

3. Ordering information

Table 1. Ordering information

Type number	Package				Version
	Temperature range	Name	Description		
74AVCH2T45DC	-40 °C to +125 °C	VSSOP8	plastic very thin shrink small outline package; 8 leads; body width 2.3 mm		SOT765-1
74AVCH2T45GT	-40 °C to +125 °C	XSON8	plastic extremely thin small outline package; no leads; 8 terminals; body 1 × 1.95 × 0.5 mm		SOT833-1
74AVCH2T45GN	-40 °C to +125 °C	XSON8	extremely thin small outline package; no leads; 8 terminals; body 1.2 × 1.0 × 0.35 mm		SOT1116
74AVCH2T45GS	-40 °C to +125 °C	XSON8	extremely thin small outline package; no leads; 8 terminals; body 1.35 × 1.0 × 0.35 mm		SOT1203

4. Marking

Table 2. Marking

Type number	Marking code [1]
74AVCH2T45DC	K45
74AVCH2T45GT	K45
74AVCH2T45GN	K5
74AVCH2T45GS	K5

[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

5. Functional diagram

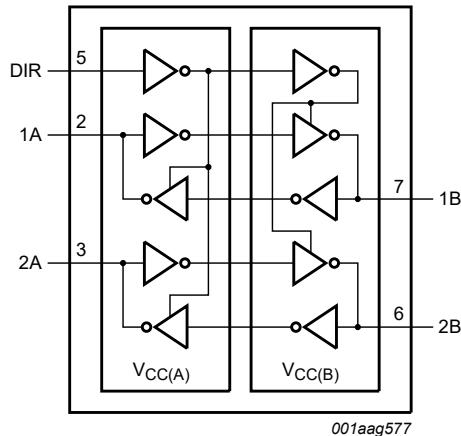


Fig. 1. Logic symbol

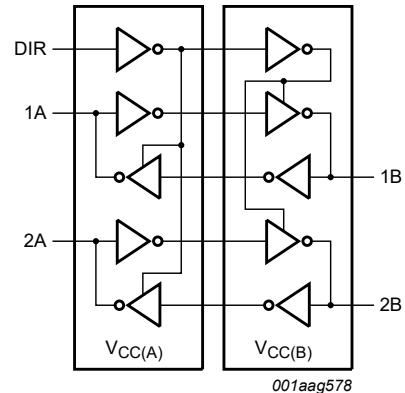
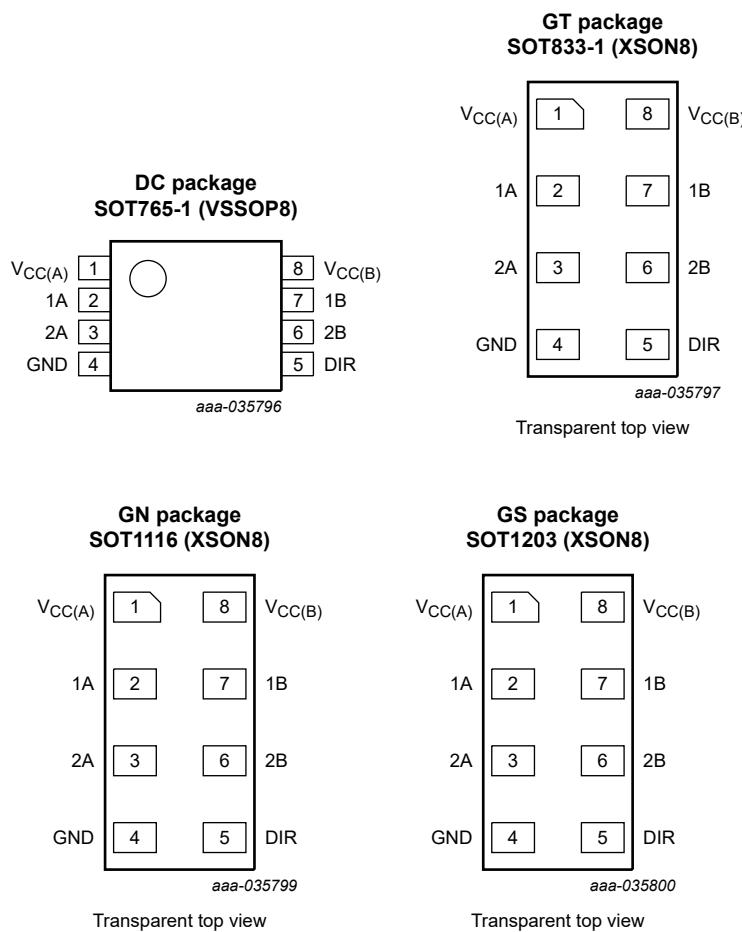


Fig. 2. Logic diagram

6. Pinning information

6.1. Pinning



6.2. Pin description

Table 3. Pin description

Symbol	Pin	Description
V _{CC(A)}	1	supply voltage port A and DIR
1A	2	data input or output
2A	3	data input or output
GND	4	ground (0 V)
DIR	5	direction control
2B	6	data input or output
1B	7	data input or output
V _{CC(B)}	8	supply voltage port B

7. Functional description

Table 4. Function table

H = HIGH voltage level; L = LOW voltage level; X = don't care; Z = high-impedance OFF-state.

Supply voltage	Input	Input/output[1]	
$V_{CC(A)}, V_{CC(B)}$	DIR[2]	nA	nB
0.8 V to 3.6 V	L	nA = nB	input
0.8 V to 3.6 V	H	input	nB = nA
GND[3]	X	Z	Z

[1] The input circuit of the data I/O is always active.

[2] The DIR input circuit is referenced to $V_{CC(A)}$.

[3] If at least one of $V_{CC(A)}$ or $V_{CC(B)}$ is at GND level, the device goes into suspend mode.

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit	
$V_{CC(A)}$	supply voltage A		-0.5	+4.6	V	
$V_{CC(B)}$	supply voltage B		-0.5	+4.6	V	
I_{IK}	input clamping current	$V_I < 0$ V	-50	-	mA	
V_I	input voltage		[1]	-0.5	+4.6	V
I_{OK}	output clamping current	$V_O < 0$ V	-50	-	mA	
V_O	output voltage	Active mode [1][2][3]	-0.5	$V_{CCO} + 0.5$	V	
		Suspend or 3-state mode [1]	-0.5	+4.6	V	
I_O	output current	$V_O = 0$ V to V_{CCO}	-	± 50	mA	
I_{CC}	supply current	$I_{CC(A)}$ or $I_{CC(B)}$	-	100	mA	
I_{GND}	ground current		-100	-	mA	
T_{stg}	storage temperature		-65	+150	°C	
P_{tot}	total power dissipation	$T_{amb} = -40$ °C to +125 °C [4]	-	250	mW	

[1] The minimum input voltage rating and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] V_{CCO} is the supply voltage associated with the output port.

[3] $V_{CCO} + 0.5$ V should not exceed 4.6 V.

[4] For SOT765-1 (VSSOP8) package: P_{tot} derates linearly with 4.9 mW/K above 99 °C.

For SOT833-1 (XSON8) package: P_{tot} derates linearly with 3.1 mW/K above 68 °C.

For SOT1116 (XSON8) package: P_{tot} derates linearly with 4.2 mW/K above 90 °C.

For SOT1203 (XSON8) package: P_{tot} derates linearly with 3.6 mW/K above 81 °C.

9. Recommended operating conditions

Table 6. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC(A)}$	supply voltage A		0.8	3.6	V
$V_{CC(B)}$	supply voltage B		0.8	3.6	V
V_I	input voltage		0	3.6	V
V_O	output voltage	Active mode [1]	0	V_{CCO}	V
		Suspend or 3-state mode	0	3.6	V
T_{amb}	ambient temperature		-40	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CCI} = 0.8 \text{ V to } 3.6 \text{ V}$	-	5	ns/V

[1] V_{CCO} is the supply voltage associated with the output port.

10. Static characteristics

Table 7. Typical static characteristics at $T_{amb} = 25 \text{ °C}$

At recommended operating conditions; voltages are referenced to GND (ground = 0 V). [1][2]

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{OH}	HIGH-level output voltage	$V_I = V_{IH}$ or V_{IL} ; $I_O = -1.5 \text{ mA}$; $V_{CC(A)} = V_{CC(B)} = 0.8 \text{ V}$	-	0.69	-	V
V_{OL}	LOW-level output voltage	$V_I = V_{IH}$ or V_{IL} ; $I_O = 1.5 \text{ mA}$; $V_{CC(A)} = V_{CC(B)} = 0.8 \text{ V}$	-	0.07	-	V
I_I	input leakage current	DIR input; $V_I = 0 \text{ V or } 3.6 \text{ V}$; $V_{CC(A)} = V_{CC(B)} = 0.8 \text{ V to } 3.6 \text{ V}$	-	± 0.025	± 0.25	μA
I_{BHL}	bus hold LOW current	$V_I = 0.42 \text{ V}$; $V_{CC(A)} = V_{CC(B)} = 1.2 \text{ V}$ [3]	-	26	-	μA
I_{BHH}	bus hold HIGH current	$V_I = 0.78 \text{ V}$; $V_{CC(A)} = V_{CC(B)} = 1.2 \text{ V}$ [4]	-	-24	-	μA
I_{BHLO}	bus hold LOW overdrive current	$V_I = \text{GND to } V_{CCI}$; $V_{CC(A)} = V_{CC(B)} = 1.2 \text{ V}$ [5]	-	28	-	μA
I_{BHHO}	bus hold HIGH overdrive current	$V_I = \text{GND to } V_{CCI}$; $V_{CC(A)} = V_{CC(B)} = 1.2 \text{ V}$ [6]	-	-26	-	μA
I_{OZ}	OFF-state output current	A or B port; $V_O = 0 \text{ V or } V_{CCO}$; $V_{CC(A)} = V_{CC(B)} = 0.8 \text{ V to } 3.6 \text{ V}$ [7]	-	± 0.5	± 2.5	μA
I_{OFF}	power-off leakage current	A port; V_I or $V_O = 0 \text{ V to } 3.6 \text{ V}$; $V_{CC(A)} = 0 \text{ V}$; $V_{CC(B)} = 0.8 \text{ V to } 3.6 \text{ V}$	-	± 0.1	± 1	μA
		B port; V_I or $V_O = 0 \text{ V to } 3.6 \text{ V}$; $V_{CC(B)} = 0 \text{ V}$; $V_{CC(A)} = 0.8 \text{ V to } 3.6 \text{ V}$	-	± 0.1	± 1	μA
C_I	input capacitance	DIR input; $V_I = 0 \text{ V or } 3.3 \text{ V}$; $V_{CC(A)} = V_{CC(B)} = 3.3 \text{ V}$	-	1.0	-	pF
$C_{I/O}$	input/output capacitance	A and B port; Suspend mode; $V_O = V_{CCO}$ or GND; $V_{CC(A)} = V_{CC(B)} = 3.3 \text{ V}$	-	4.0	-	pF

[1] V_{CCO} is the supply voltage associated with the output port.

[2] V_{CCI} is the supply voltage associated with the data input port.

[3] The bus hold circuit can sink at least the minimum low sustaining current at V_{IL} max.

I_{BHL} should be measured after lowering V_I to GND and then raising it to V_{IL} max.

[4] The bus hold circuit can source at least the minimum high sustaining current at V_{IH} min.

I_{BHH} should be measured after raising V_I to V_{CC} and then lowering it to V_{IH} min.

[5] An external driver must source at least I_{BHLO} to switch this node from LOW to HIGH.

[6] An external driver must sink at least I_{BHHO} to switch this node from HIGH to LOW.

[7] For I/O ports, the parameter I_{OZ} includes the input leakage current.

Table 8. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).^{[1][2]}

Symbol	Parameter	Conditions	-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Max	Min	Max	
V _{IH}	HIGH-level input voltage	data input					
		V _{CCI} = 0.8 V	0.70V _{CCI}	-	0.70V _{CCI}	-	V
		V _{CCI} = 1.1 V to 1.95 V	0.65V _{CCI}	-	0.65V _{CCI}	-	V
		V _{CCI} = 2.3 V to 2.7 V	1.6	-	1.6	-	V
		V _{CCI} = 3.0 V to 3.6 V	2	-	2	-	V
		DIR input					
		V _{CC(A)} = 0.8 V	0.70V _{CC(A)}	-	0.70V _{CC(A)}	-	V
		V _{CC(A)} = 1.1 V to 1.95 V	0.65V _{CC(A)}	-	0.65V _{CC(A)}	-	V
		V _{CC(A)} = 2.3 V to 2.7 V	1.6	-	1.6	-	V
		V _{CC(A)} = 3.0 V to 3.6 V	2	-	2	-	V
V _{IL}	LOW-level input voltage	data input					
		V _{CCI} = 0.8 V	-	0.30V _{CCI}	-	0.30V _{CCI}	V
		V _{CCI} = 1.1 V to 1.95 V	-	0.35V _{CCI}	-	0.35V _{CCI}	V
		V _{CCI} = 2.3 V to 2.7 V	-	0.7	-	0.7	V
		V _{CCI} = 3.0 V to 3.6 V	-	0.9	-	0.9	V
		DIR input					
		V _{CC(A)} = 0.8 V	-	0.30V _{CC(A)}	-	0.30V _{CC(A)}	V
		V _{CC(A)} = 1.1 V to 1.95 V	-	0.35V _{CC(A)}	-	0.35V _{CC(A)}	V
		V _{CC(A)} = 2.3 V to 2.7 V	-	0.7	-	0.7	V
		V _{CC(A)} = 3.0 V to 3.6 V	-	0.9	-	0.9	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL}					
		I _O = -100 μ A; V _{CC(A)} = V _{CC(B)} = 0.8 V to 3.6 V	V _{CCO} - 0.1	-	V _{CCO} - 0.1	-	V
		I _O = -3 mA; V _{CC(A)} = V _{CC(B)} = 1.1 V	0.85	-	0.85	-	V
		I _O = -6 mA; V _{CC(A)} = V _{CC(B)} = 1.4 V	1.05	-	1.05	-	V
		I _O = -8 mA; V _{CC(A)} = V _{CC(B)} = 1.65 V	1.2	-	1.2	-	V
		I _O = -9 mA; V _{CC(A)} = V _{CC(B)} = 2.3 V	1.75	-	1.75	-	V
		I _O = -12 mA; V _{CC(A)} = V _{CC(B)} = 3.0 V	2.3	-	2.3	-	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL}					
		I _O = 100 μ A; V _{CC(A)} = V _{CC(B)} = 0.8 V to 3.6 V	-	0.1	-	0.1	V
		I _O = 3 mA; V _{CC(A)} = V _{CC(B)} = 1.1 V	-	0.25	-	0.25	V
		I _O = 6 mA; V _{CC(A)} = V _{CC(B)} = 1.4 V	-	0.35	-	0.35	V
		I _O = 8 mA; V _{CC(A)} = V _{CC(B)} = 1.65 V	-	0.45	-	0.45	V
		I _O = 9 mA; V _{CC(A)} = V _{CC(B)} = 2.3 V	-	0.55	-	0.55	V
		I _O = 12 mA; V _{CC(A)} = V _{CC(B)} = 3.0 V	-	0.7	-	0.7	V
I _I	input leakage current	DIR input; V _I = 0 V or 3.6 V; V _{CC(A)} = V _{CC(B)} = 0.8 V to 3.6 V	-	\pm 1	-	\pm 1.5	μ A

Symbol	Parameter	Conditions	-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Max	Min	Max	
I _{BHL}	bus hold LOW current	A or B port [3]					
		$V_I = 0.49 \text{ V}; V_{CC(A)} = V_{CC(B)} = 1.4 \text{ V}$	15	-	15	-	µA
		$V_I = 0.58 \text{ V}; V_{CC(A)} = V_{CC(B)} = 1.65 \text{ V}$	25	-	25	-	µA
		$V_I = 0.70 \text{ V}; V_{CC(A)} = V_{CC(B)} = 2.3 \text{ V}$	45	-	45	-	µA
		$V_I = 0.80 \text{ V}; V_{CC(A)} = V_{CC(B)} = 3.0 \text{ V}$	100	-	90	-	µA
I _{BHH}	bus hold HIGH current	A or B port [4]					
		$V_I = 0.91 \text{ V}; V_{CC(A)} = V_{CC(B)} = 1.4 \text{ V}$	-15	-	-15	-	µA
		$V_I = 1.07 \text{ V}; V_{CC(A)} = V_{CC(B)} = 1.65 \text{ V}$	-25	-	-25	-	µA
		$V_I = 1.60 \text{ V}; V_{CC(A)} = V_{CC(B)} = 2.3 \text{ V}$	-45	-	-45	-	µA
		$V_I = 2.00 \text{ V}; V_{CC(A)} = V_{CC(B)} = 3.0 \text{ V}$	-100	-	-100	-	µA
I _{BHLO}	bus hold LOW overdrive current	A or B port [5]					
		$V_{CC(A)} = V_{CC(B)} = 1.6 \text{ V}$	125	-	125	-	µA
		$V_{CC(A)} = V_{CC(B)} = 1.95 \text{ V}$	200	-	200	-	µA
		$V_{CC(A)} = V_{CC(B)} = 2.7 \text{ V}$	300	-	300	-	µA
		$V_{CC(A)} = V_{CC(B)} = 3.6 \text{ V}$	500	-	500	-	µA
I _{BHHO}	bus hold HIGH overdrive current	A or B port [6]					
		$V_{CC(A)} = V_{CC(B)} = 1.6 \text{ V}$	-125	-	-125	-	µA
		$V_{CC(A)} = V_{CC(B)} = 1.95 \text{ V}$	-200	-	-200	-	µA
		$V_{CC(A)} = V_{CC(B)} = 2.7 \text{ V}$	-300	-	-300	-	µA
		$V_{CC(A)} = V_{CC(B)} = 3.6 \text{ V}$	-500	-	-500	-	µA
I _{OZ}	OFF-state output current	A or B port; $V_O = 0 \text{ V}$ or V_{CCO} ; $V_{CC(A)} = V_{CC(B)} = 0.8 \text{ to } 3.6 \text{ V}$ [7]	-	±5	-	±7.5	µA
I _{OFF}	power-off leakage current	A port; V_I or $V_O = 0 \text{ V}$ to 3.6 V ; $V_{CC(A)} = 0 \text{ V}$; $V_{CC(B)} = 0.8 \text{ V}$ to 3.6 V	-	±5	-	±35	µA
		B port; V_I or $V_O = 0 \text{ V}$ to 3.6 V ; $V_{CC(B)} = 0 \text{ V}$; $V_{CC(A)} = 0.8 \text{ V}$ to 3.6 V	-	±5	-	±35	µA
I _{CC}	supply current	A port; $V_I = 0 \text{ V}$ or V_{CCI} ; $I_O = 0 \text{ A}$					
		$V_{CC(A)} = 0.8 \text{ V}$ to 3.6 V ; $V_{CC(B)} = 0.8 \text{ V}$ to 3.6 V	-	8	-	11.5	µA
		$V_{CC(A)} = 3.6 \text{ V}$; $V_{CC(B)} = 0 \text{ V}$	-	8	-	11.5	µA
		$V_{CC(A)} = 0 \text{ V}$; $V_{CC(B)} = 3.6 \text{ V}$	-2	-	-8	-	µA
		B port; $V_I = 0 \text{ V}$ or V_{CCI} ; $I_O = 0 \text{ A}$					
		$V_{CC(A)} = 0.8 \text{ V}$ to 3.6 V ; $V_{CC(B)} = 0.8 \text{ V}$ to 3.6 V	-	8	-	11.5	µA
		$V_{CC(A)} = 3.6 \text{ V}$; $V_{CC(B)} = 0 \text{ V}$	-2	-	-8	-	µA
		$V_{CC(A)} = 0 \text{ V}$; $V_{CC(B)} = 3.6 \text{ V}$	-	8	-	11.5	µA
		A plus B port ($I_{CC(A)} + I_{CC(B)}$); $I_O = 0 \text{ A}$; $V_I = 0 \text{ V}$ or V_{CCI} ; $V_{CC(A)} = 0.8 \text{ V}$ to 3.6 V ; $V_{CC(B)} = 0.8 \text{ V}$ to 3.6 V	-	16	-	23	µA

[1] V_{CCO} is the supply voltage associated with the output port.

[2] V_{CCI} is the supply voltage associated with the data input port.

[3] The bus hold circuit can sink at least the minimum low sustaining current at V_{IL} max.

I_{BHL} should be measured after lowering V_I to GND and then raising it to V_{IL} max.

[4] The bus hold circuit can source at least the minimum high sustaining current at V_{IH} min.

I_{BH} should be measured after raising V_I to V_{CC} and then lowering it to V_{IH} min.

[5] An external driver must source at least I_{BHLO} to switch this node from LOW to HIGH.

[6] An external driver must sink at least I_{BHHO} to switch this node from HIGH to LOW.

[7] For I/O ports, the parameter I_{OZ} includes the input leakage current.

11. Dynamic characteristics

Table 9. Typical dynamic characteristics at $V_{CC(A)} = 0.8 \text{ V}$ and $T_{amb} = 25 \text{ }^{\circ}\text{C}$

Voltages are referenced to GND (ground = 0 V); for test circuit see [Fig. 5](#); for waveforms see [Fig. 3](#) and [Fig. 4](#). [1] [2]

Symbol	Parameter	Conditions	$V_{CC(B)}$						Unit
			0.8 V	1.2 V	1.5 V	1.8 V	2.5 V	3.3 V	
t_{pd}	propagation delay	A to B	15.8	8.4	8.0	8.0	8.7	9.5	ns
		B to A	15.8	12.7	12.4	12.2	12.0	11.8	ns
t_{dis}	disable time	DIR to A	12.2	12.2	12.2	12.2	12.2	12.2	ns
		DIR to B	11.7	7.9	7.6	8.2	8.7	10.2	ns
t_{en}	enable time	DIR to A	27.5	20.6	20.0	20.4	20.7	22.0	ns
		DIR to B	28.0	20.6	20.2	20.2	20.9	21.7	ns

[1] t_{pd} is the same as t_{PLH} and t_{PHL} ; t_{dis} is the same as t_{PLZ} and t_{PHZ} ; t_{en} is the same as t_{PZL} and t_{PZH} .

[2] t_{en} is a calculated value using the formula shown in [Section 12.4](#).

Table 10. Typical dynamic characteristics at $V_{CC(B)} = 0.8 \text{ V}$ and $T_{amb} = 25 \text{ }^{\circ}\text{C}$

Voltages are referenced to GND (ground = 0 V); for test circuit see [Fig. 5](#); for waveforms see [Fig. 3](#) and [Fig. 4](#). [1] [2]

Symbol	Parameter	Conditions	$V_{CC(A)}$						Unit
			0.8 V	1.2 V	1.5 V	1.8 V	2.5 V	3.3 V	
t_{pd}	propagation delay	A to B	15.8	12.7	12.4	12.2	12.0	11.8	ns
		B to A	15.8	8.4	8.0	8.0	8.7	9.5	ns
t_{dis}	disable time	DIR to A	12.2	4.9	3.8	3.7	2.8	3.4	ns
		DIR to B	11.7	9.2	9.0	8.8	8.7	8.6	ns
t_{en}	enable time	DIR to A	27.5	17.6	17.0	16.8	17.4	18.1	ns
		DIR to B	28.0	17.6	16.2	15.9	14.8	15.2	ns

[1] t_{pd} is the same as t_{PLH} and t_{PHL} ; t_{dis} is the same as t_{PLZ} and t_{PHZ} ; t_{en} is the same as t_{PZL} and t_{PZH} .

[2] t_{en} is a calculated value using the formula shown in [Section 12.4](#).

Table 11. Typical power dissipation capacitance at $V_{CC(A)} = V_{CC(B)}$ and $T_{amb} = 25 \text{ }^{\circ}\text{C}$

Voltages are referenced to GND (ground = 0 V). [1] [2]

Symbol	Parameter	Conditions	$V_{CC(A)}$ and $V_{CC(B)}$						Unit
			0.8 V	1.2 V	1.5 V	1.8 V	2.5 V	3.3 V	
C_{PD}	power dissipation capacitance	A port: (direction A to B); B port: (direction B to A)	1	2	2	2	2	2	pF
		A port: (direction B to A); B port: (direction A to B)	9	11	11	12	14	17	pF

[1] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum(C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

f_i = input frequency in MHz;

f_o = output frequency in MHz;

C_L = load capacitance in pF;

V_{CC} = supply voltage in V;

N = number of inputs switching;

$\sum(C_L \times V_{CC}^2 \times f_o)$ = sum of the outputs.

[2] $f_i = 10 \text{ MHz}$; $V_I = \text{GND to } V_{CC}$; $t_r = t_f = 1 \text{ ns}$; $C_L = 0 \text{ pF}$; $R_L = \infty \Omega$.

Table 12. Dynamic characteristics for temperature range -40 °C to +85 °CVoltages are referenced to GND (ground = 0 V); for test circuit see [Fig. 5](#); for waveforms see [Fig. 3](#) and [Fig. 4](#). [\[1\]](#)/[\[2\]](#)

Symbol	Parameter	Conditions	V _{CC(B)}										Unit	
			1.2 V ± 0.1 V		1.5 V ± 0.1 V		1.8 V ± 0.15 V		2.5 V ± 0.2 V		3.3 V ± 0.3 V			
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max		
V_{CC(A)} = 1.1 V to 1.3 V														
t _{pd}	propagation delay	A to B	1.0	9.0	0.7	6.8	0.6	6.1	0.5	5.7	0.5	6.1	ns	
		B to A	1.0	9.0	0.8	8.0	0.7	7.7	0.6	7.2	0.5	7.1	ns	
t _{dis}	disable time	DIR to A	2.2	8.8	2.2	8.8	2.2	8.8	2.2	8.8	2.2	8.8	ns	
		DIR to B	2.2	8.4	1.8	6.7	2.0	6.9	1.7	6.2	2.4	7.2	ns	
t _{en}	enable time	DIR to A	-	17.4	-	14.7	-	14.6	-	13.4	-	14.3	ns	
		DIR to B	-	17.8	-	15.6	-	14.9	-	14.5	-	14.9	ns	
V_{CC(A)} = 1.4 V to 1.6 V														
t _{pd}	propagation delay	A to B	1.0	8.0	0.7	5.4	0.6	4.6	0.5	3.7	0.5	3.5	ns	
		B to A	1.0	6.8	0.8	5.4	0.7	5.1	0.6	4.7	0.5	4.5	ns	
t _{dis}	disable time	DIR to A	1.6	6.3	1.6	6.3	1.6	6.3	1.6	6.3	1.6	6.3	ns	
		DIR to B	2.0	7.6	1.8	5.9	1.6	6.0	1.2	4.8	1.7	5.5	ns	
t _{en}	enable time	DIR to A	-	14.4	-	11.3	-	11.1	-	9.5	-	10.0	ns	
		DIR to B	-	14.3	-	11.7	-	10.9	-	10.0	-	9.8	ns	
V_{CC(A)} = 1.65 V to 1.95 V														
t _{pd}	propagation delay	A to B	1.0	7.7	0.6	5.1	0.5	4.3	0.5	3.4	0.5	3.1	ns	
		B to A	1.0	6.1	0.7	4.6	0.5	4.4	0.5	3.9	0.5	3.7	ns	
t _{dis}	disable time	DIR to A	1.6	5.5	1.6	5.5	1.6	5.5	1.6	5.5	1.6	5.5	ns	
		DIR to B	1.8	7.8	1.8	5.7	1.4	5.8	1.0	4.5	1.5	5.2	ns	
t _{en}	enable time	DIR to A	-	13.9	-	10.3	-	10.2	-	8.4	-	8.9	ns	
		DIR to B	-	13.2	-	10.6	-	9.8	-	8.9	-	8.6	ns	
V_{CC(A)} = 2.3 V to 2.7 V														
t _{pd}	propagation delay	A to B	1.0	7.2	0.5	4.7	0.5	3.9	0.5	3.0	0.5	2.6	ns	
		B to A	1.0	5.7	0.6	3.8	0.5	3.4	0.5	3.0	0.5	2.8	ns	
t _{dis}	disable time	DIR to A	1.5	4.2	1.5	4.2	1.5	4.2	1.5	4.2	1.5	4.2	ns	
		DIR to B	1.7	7.3	2.0	5.2	1.5	5.1	0.6	4.2	1.1	4.8	ns	
t _{en}	enable time	DIR to A	-	13.0	-	9.0	-	8.5	-	7.2	-	7.6	ns	
		DIR to B	-	11.4	-	8.9	-	8.1	-	7.2	-	6.8	ns	
V_{CC(A)} = 3.0 V to 3.6 V														
t _{pd}	propagation delay	A to B	1.0	7.1	0.5	4.5	0.5	3.7	0.5	2.8	0.5	2.4	ns	
		B to A	1.0	6.1	0.6	3.6	0.5	3.1	0.5	2.6	0.5	2.4	ns	
t _{dis}	disable time	DIR to A	1.5	4.7	1.5	4.7	1.5	4.7	1.5	4.7	1.5	4.7	ns	
		DIR to B	1.7	7.2	0.7	5.5	0.6	5.5	0.7	4.1	1.7	4.7	ns	
t _{en}	enable time	DIR to A	-	13.3	-	9.1	-	8.6	-	6.7	-	7.1	ns	
		DIR to B	-	11.8	-	9.2	-	8.4	-	7.5	-	7.1	ns	

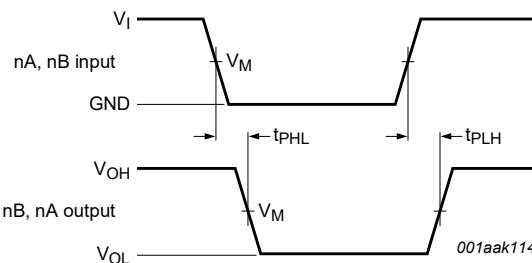
[1] t_{pd} is the same as t_{PLH} and t_{PHL}; t_{dis} is the same as t_{PLZ} and t_{PHZ}; t_{en} is the same as t_{PZL} and t_{PZH}.[2] t_{en} is a calculated value using the formula shown in [Section 12.4](#).

Table 13. Dynamic characteristics for temperature range -40 °C to +125 °CVoltages are referenced to GND (ground = 0 V); for test circuit see [Fig. 5](#); for waveforms see [Fig. 3](#) and [Fig. 4](#). [\[1\]](#) [\[2\]](#)

Symbol	Parameter	Conditions	V _{CC(B)}										Unit	
			1.2 V ± 0.1 V		1.5 V ± 0.1 V		1.8 V ± 0.15 V		2.5 V ± 0.2 V		3.3 V ± 0.3 V			
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max		
V_{CC(A)} = 1.1 V to 1.3 V														
t _{pd}	propagation delay	A to B	1.0	9.9	0.7	7.5	0.6	6.8	0.5	6.3	0.5	6.8	ns	
		B to A	1.0	9.9	0.8	8.8	0.7	8.5	0.6	8.0	0.5	7.9	ns	
t _{dis}	disable time	DIR to A	2.2	9.7	2.2	9.7	2.2	9.7	2.2	9.7	2.2	9.7	ns	
		DIR to B	2.2	9.2	1.8	7.4	2.0	7.6	1.7	6.9	2.4	8.0	ns	
t _{en}	enable time	DIR to A	-	19.1	-	16.2	-	16.1	-	14.9	-	15.9	ns	
		DIR to B	-	19.6	-	17.2	-	16.5	-	16.0	-	16.5	ns	
V_{CC(A)} = 1.4 V to 1.6 V														
t _{pd}	propagation delay	A to B	1.0	8.8	0.7	6.0	0.6	5.1	0.5	4.1	0.5	3.9	ns	
		B to A	1.0	7.5	0.8	6.0	0.7	5.7	0.6	5.2	0.5	5.0	ns	
t _{dis}	disable time	DIR to A	1.6	7.0	1.6	7.0	1.6	7.0	1.6	7.0	1.6	7.0	ns	
		DIR to B	2.0	8.3	1.8	6.5	1.6	6.6	1.2	5.3	1.7	6.1	ns	
t _{en}	enable time	DIR to A	-	15.8	-	12.5	-	12.3	-	10.5	-	11.1	ns	
		DIR to B	-	15.8	-	13.0	-	12.7	-	11.1	-	10.9	ns	
V_{CC(A)} = 1.65 V to 1.95 V														
t _{pd}	propagation delay	A to B	1.0	8.5	0.6	5.7	0.5	4.8	0.5	3.8	0.5	3.5	ns	
		B to A	1.0	6.8	0.7	5.1	0.5	4.9	0.5	4.3	0.5	4.1	ns	
t _{dis}	disable time	DIR to A	1.6	6.1	1.6	6.1	1.6	6.1	1.6	6.1	1.6	6.1	ns	
		DIR to B	1.8	8.6	1.8	6.3	1.4	6.4	1.0	5.0	1.5	5.8	ns	
t _{en}	enable time	DIR to A	-	15.4	-	11.4	-	11.3	-	9.3	-	9.9	ns	
		DIR to B	-	14.6	-	11.8	-	10.9	-	9.9	-	9.6	ns	
V_{CC(A)} = 2.3 V to 2.7 V														
t _{pd}	propagation delay	A to B	1.0	8.0	0.5	5.2	0.5	4.3	0.5	3.3	0.5	2.9	ns	
		B to A	1.0	6.3	0.6	4.2	0.5	3.8	0.5	3.3	0.5	3.1	ns	
t _{dis}	disable time	DIR to A	1.5	4.7	1.5	4.7	1.5	4.7	1.5	4.7	1.5	4.7	ns	
		DIR to B	1.7	8.0	2.0	5.8	1.5	5.7	0.6	4.7	1.1	5.3	ns	
t _{en}	enable time	DIR to A	-	14.3	-	10.0	-	9.5	-	8.0	-	8.4	ns	
		DIR to B	-	12.7	-	9.9	-	9.0	-	8.0	-	7.6	ns	
V_{CC(A)} = 3.0 V to 3.6 V														
t _{pd}	propagation delay	A to B	1.0	7.9	0.5	5.0	0.5	4.1	0.5	3.1	0.5	2.7	ns	
		B to A	1.0	6.8	0.6	4.0	0.5	3.5	0.5	2.9	0.5	2.7	ns	
t _{dis}	disable time	DIR to A	1.5	5.2	1.5	5.2	1.5	5.2	1.5	5.2	1.5	5.2	ns	
		DIR to B	1.7	7.9	0.7	6.1	0.6	6.1	0.7	4.6	1.7	5.2	ns	
t _{en}	enable time	DIR to A	-	14.7	-	10.1	-	9.6	-	7.5	-	7.9	ns	
		DIR to B	-	13.1	-	10.2	-	9.3	-	8.3	-	7.9	ns	

[1] t_{pd} is the same as t_{PLH} and t_{PHL}; t_{dis} is the same as t_{PLZ} and t_{PHZ}; t_{en} is the same as t_{PZL} and t_{PZH}.[2] t_{en} is a calculated value using the formula shown in [Section 12.4](#).

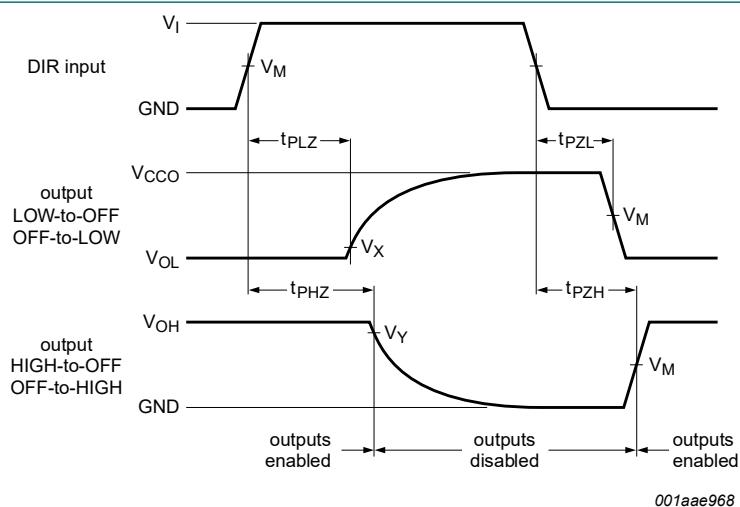
11.1. Waveforms and test circuit



Measurement points are given in [Table 14](#).

V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Fig. 3. The data input (nA, nB) to output (nB, nA) propagation delay times



Measurement points are given in [Table 14](#).

V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

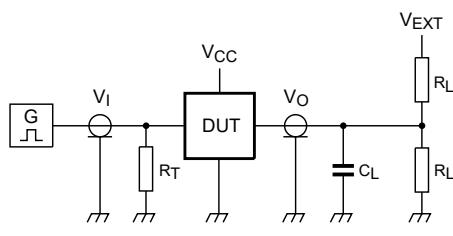
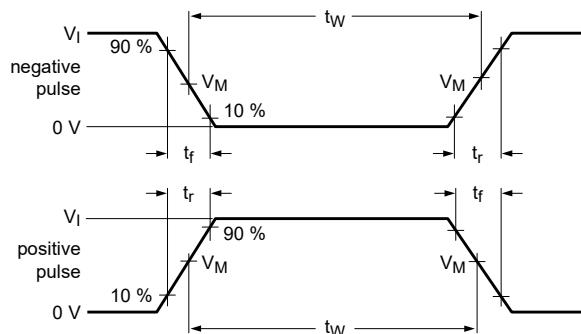
Fig. 4. 3-state enable and disable times

Table 14. Measurement points

Supply voltage	Input[1]	Output[2]		
$V_{CC(A)}, V_{CC(B)}$	V_M	V_M	V_X	V_Y
1.1 V to 1.6 V	$0.5V_{CCI}$	$0.5V_{CCO}$	$V_{OL} + 0.1$ V	$V_{OH} - 0.1$ V
1.65 V to 2.7 V	$0.5V_{CCI}$	$0.5V_{CCO}$	$V_{OL} + 0.15$ V	$V_{OH} - 0.15$ V
3.0 V to 3.6 V	$0.5V_{CCI}$	$0.5V_{CCO}$	$V_{OL} + 0.3$ V	$V_{OH} - 0.3$ V

[1] V_{CCI} is the supply voltage associated with the data input port.

[2] V_{CCO} is the supply voltage associated with the output port.



001aae331

Test data is given in [Table 15](#).

Definitions test circuit:

R_L = Load resistance;

C_L = Load capacitance including jig and probe capacitance;

R_T = Termination resistance;

V_{EXT} = External voltage for measuring switching times.

Fig. 5. Test circuit for measuring switching times

Table 15. Test data

Supply voltage	Input	Load	V_{EXT}
$V_{CC(A)}$, $V_{CC(B)}$	V_I [1]	$\Delta t/\Delta V$ [2]	t_{PLH} , t_{PHL}
1.1 V to 1.6 V	V_{CCI}	$\leq 1.0 \text{ ns/V}$	t_{PZH} , t_{PHZ}
1.65 V to 2.7 V	V_{CCI}	$\leq 1.0 \text{ ns/V}$	t_{PZL} , t_{PLZ} [3]
3.0 V to 3.6 V	V_{CCI}	$\leq 1.0 \text{ ns/V}$	$2V_{CCO}$

[1] V_{CCI} is the supply voltage associated with the data input port.

[2] $dV/dt \geq 1.0 \text{ V/ns}$

[3] V_{CCO} is the supply voltage associated with the output port.

12. Application information

12.1. Unidirectional logic level-shifting application

The circuit given in [Fig. 6](#) is an example of the 74AVCH2T45 being used in an unidirectional logic level-shifting application.

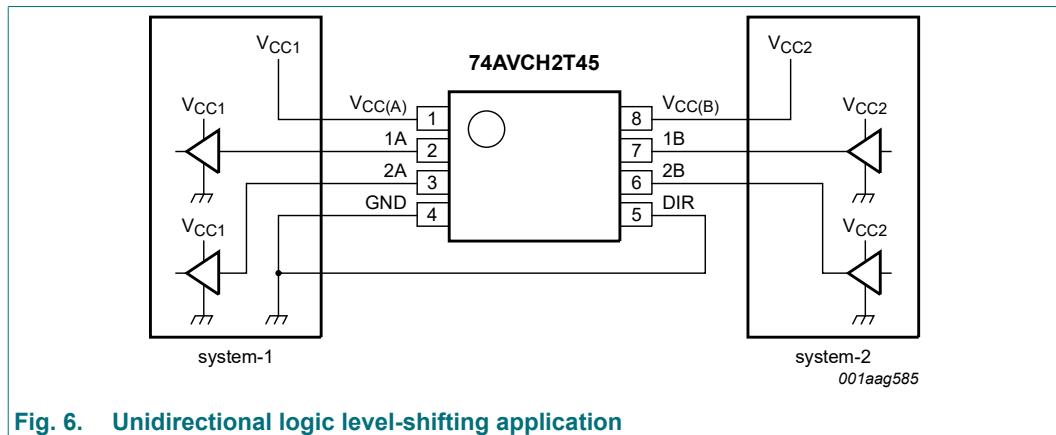


Fig. 6. Unidirectional logic level-shifting application

Table 16. Unidirectional logic level-shifting application

Pin	Name	Function	Description
1	$V_{CC(A)}$	V_{CC1}	supply voltage of system-1 (0.8 V to 3.6 V)
2	1A	OUT1	output level depends on V_{CC1} voltage
3	2A	OUT2	output level depends on V_{CC1} voltage
4	GND	GND	device GND
5	DIR	DIR	the GND (LOW level) determines B port to A port direction
6	2B	IN2	input threshold value depends on V_{CC2} voltage
7	1B	IN1	input threshold value depends on V_{CC2} voltage
8	$V_{CC(B)}$	V_{CC2}	supply voltage of system-2 (0.8 V to 3.6 V)

12.2. Bidirectional logic level-shifting application

Fig. 7 shows the 74AVCH2T45 being used in a bidirectional logic level-shifting application. Since the device does not have an output enable (OE) pin, the system designer should take precautions to avoid bus contention between system-1 and system-2 when changing directions.

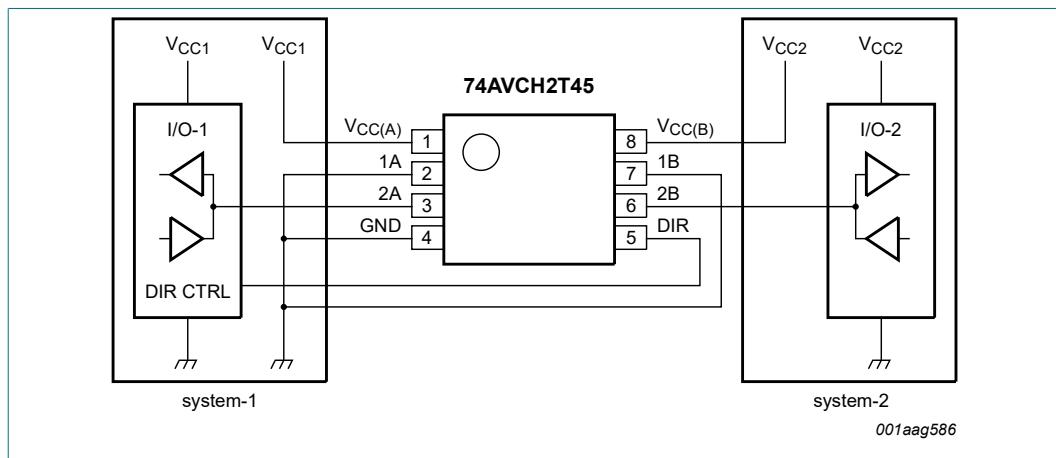


Fig. 7. Bidirectional logic level-shifting application

[Table 17](#) gives a sequence that will illustrate data transmission from system-1 to system-2 and then from system-2 to system-1.

Table 17. Bidirectional logic level-shifting application [1]

State	DIR CTRL	I/O-1	I/O-2	Description
1	H	output	input	system-1 data to system-2
2	H	Z	Z	system-2 is getting ready to send data to system-1. I/O-1 and I/O-2 are disabled. The bus-line state depends on bus hold.
3	L	Z	Z	DIR bit is set LOW. I/O-1 and I/O-2 still are disabled. The bus-line state depends on bus hold.
4	L	input	output	system-2 data to system-1

[1] H = HIGH voltage level;
L = LOW voltage level;
Z = high-impedance OFF-state.

12.3. Power-up considerations

The device is designed such that no special power-up sequence is required other than GND being applied first.

Table 18. Typical total supply current ($I_{CC(A)} + I_{CC(B)}$)

$V_{CC(A)}$	$V_{CC(B)}$							Unit
	0 V	0.8 V	1.2 V	1.5 V	1.8 V	2.5 V	3.3 V	
0 V	0	0.1	0.1	0.1	0.1	0.1	0.1	µA
0.8 V	0.1	0.1	0.1	0.1	0.1	0.7	2.3	µA
1.2 V	0.1	0.1	0.1	0.1	0.1	0.3	1.4	µA
1.5 V	0.1	0.1	0.1	0.1	0.1	0.1	0.9	µA
1.8 V	0.1	0.1	0.1	0.1	0.1	0.1	0.5	µA
2.5 V	0.1	0.7	0.3	0.1	0.1	0.1	0.1	µA
3.3 V	0.1	2.3	1.4	0.9	0.5	0.1	0.1	µA

12.4. Enable times

The enable times for the 74AVCH2T45 are calculated from the following formulas:

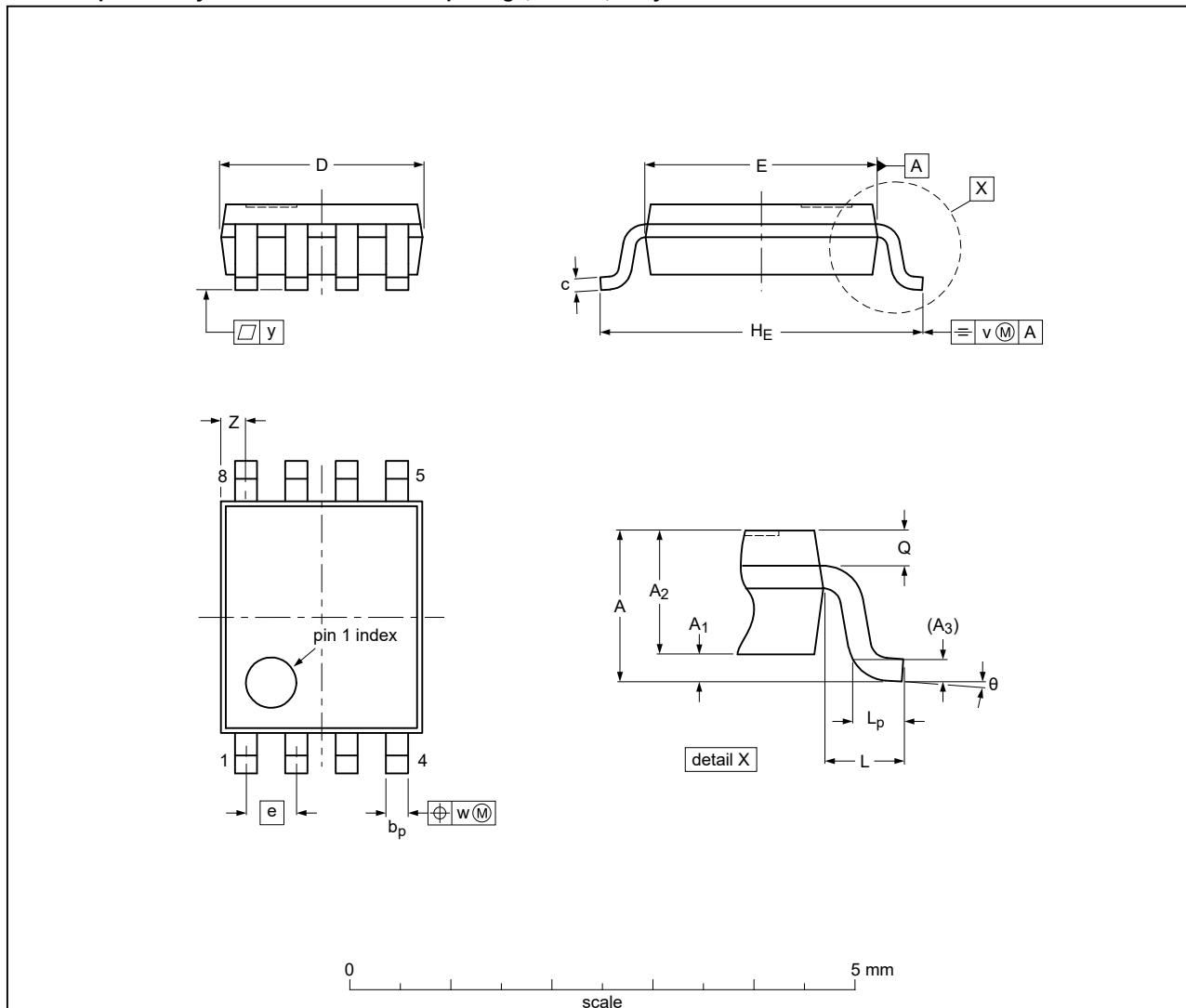
- t_{en} (DIR to nA) = t_{dis} (DIR to nB) + t_{pd} (nB to nA)
- t_{en} (DIR to nB) = t_{dis} (DIR to nA) + t_{pd} (nA to nB)

In a bidirectional application, these enable times provide the maximum delay from the time the DIR bit is switched until an output is expected. For example, if the 74AVCH2T45 initially is transmitting from A to B, then the DIR bit is switched, the B port of the device must be disabled before presenting it with an input. After the B port has been disabled, an input signal applied to it appears on the corresponding A port after the specified propagation delay.

13. Package outline

VSSOP8: plastic very thin shrink small outline package; 8 leads; body width 2.3 mm

SOT765-1



Dimensions (mm are the original dimensions)

Unit	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽²⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	max	0.15	0.85		0.27	0.23	2.1	2.4		3.2	0.4	0.40	0.21	0.2	0.08	0.1	0.4	8°
mm	nom	1		0.12				0.5		0.4				0.2	0.08	0.1	0.1	0°
	min	0.00	0.60		0.17	0.08	1.9	2.2		3.0	0.15	0.19						

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

sot765-1_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT765-1		MO-187				07-06-02 16-05-31

Fig. 8. Package outline SOT765-1 (VSSOP8)

XSON8: plastic extremely thin small outline package; no leads; 8 terminals; body 1 x 1.95 x 0.5 mm

SOT833-1

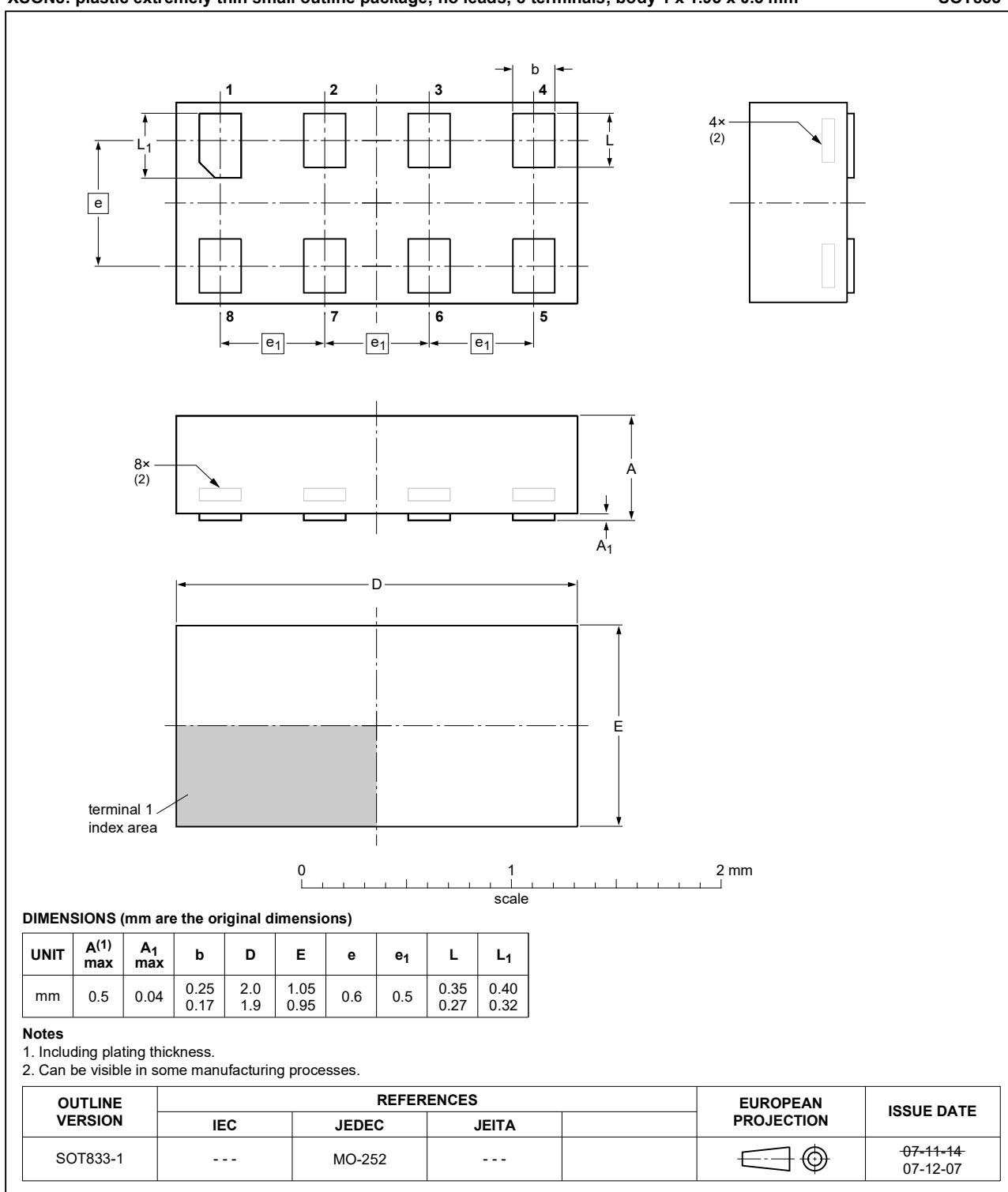


Fig. 9. Package outline SOT833-1 (XSON8)

XSON8: extremely thin small outline package; no leads;
8 terminals; body 1.2 x 1.0 x 0.35 mm

SOT1116

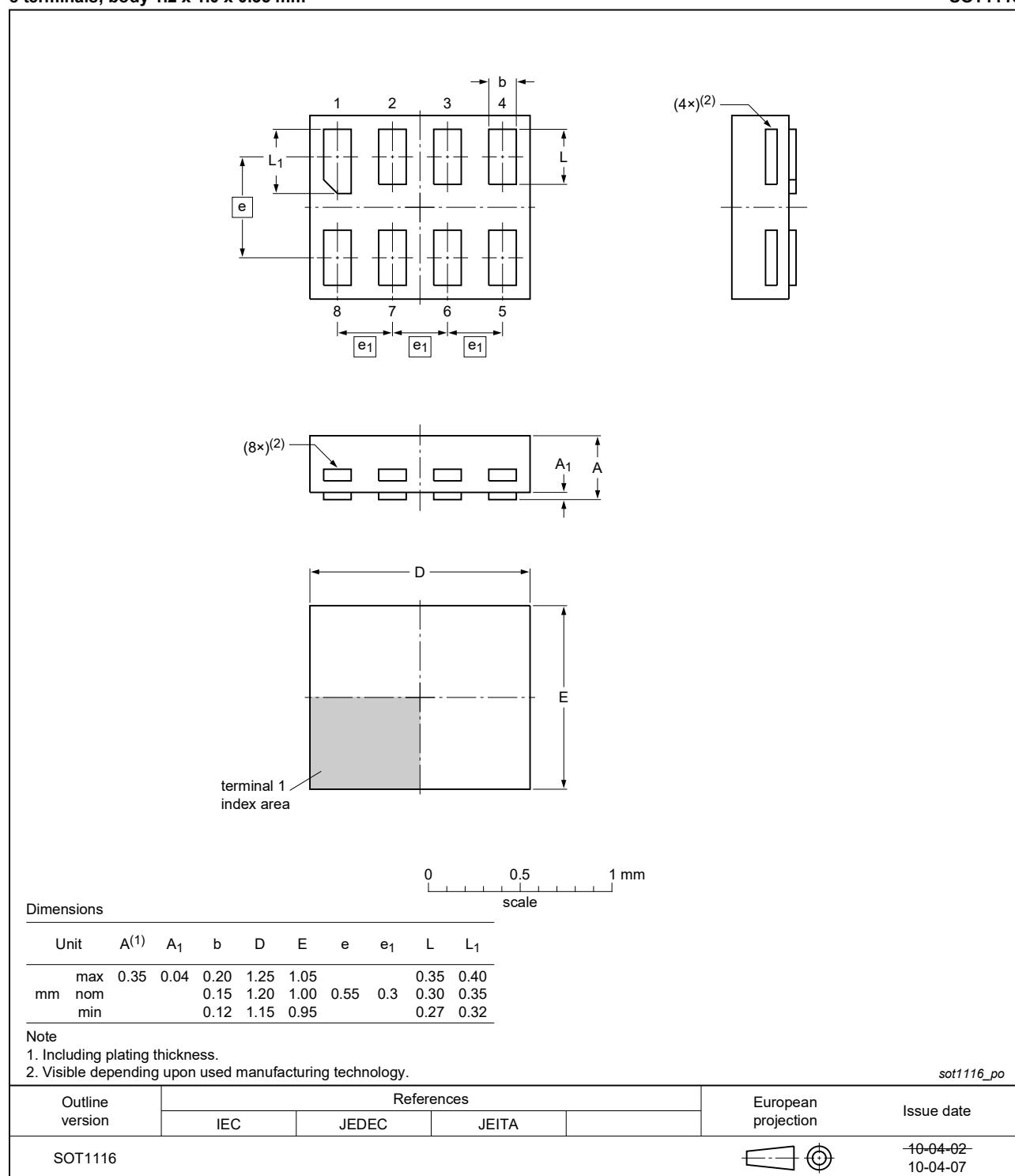


Fig. 10. Package outline SOT1116 (XSON8)

XSON8: extremely thin small outline package; no leads;
8 terminals; body 1.35 x 1.0 x 0.35 mm

SOT1203

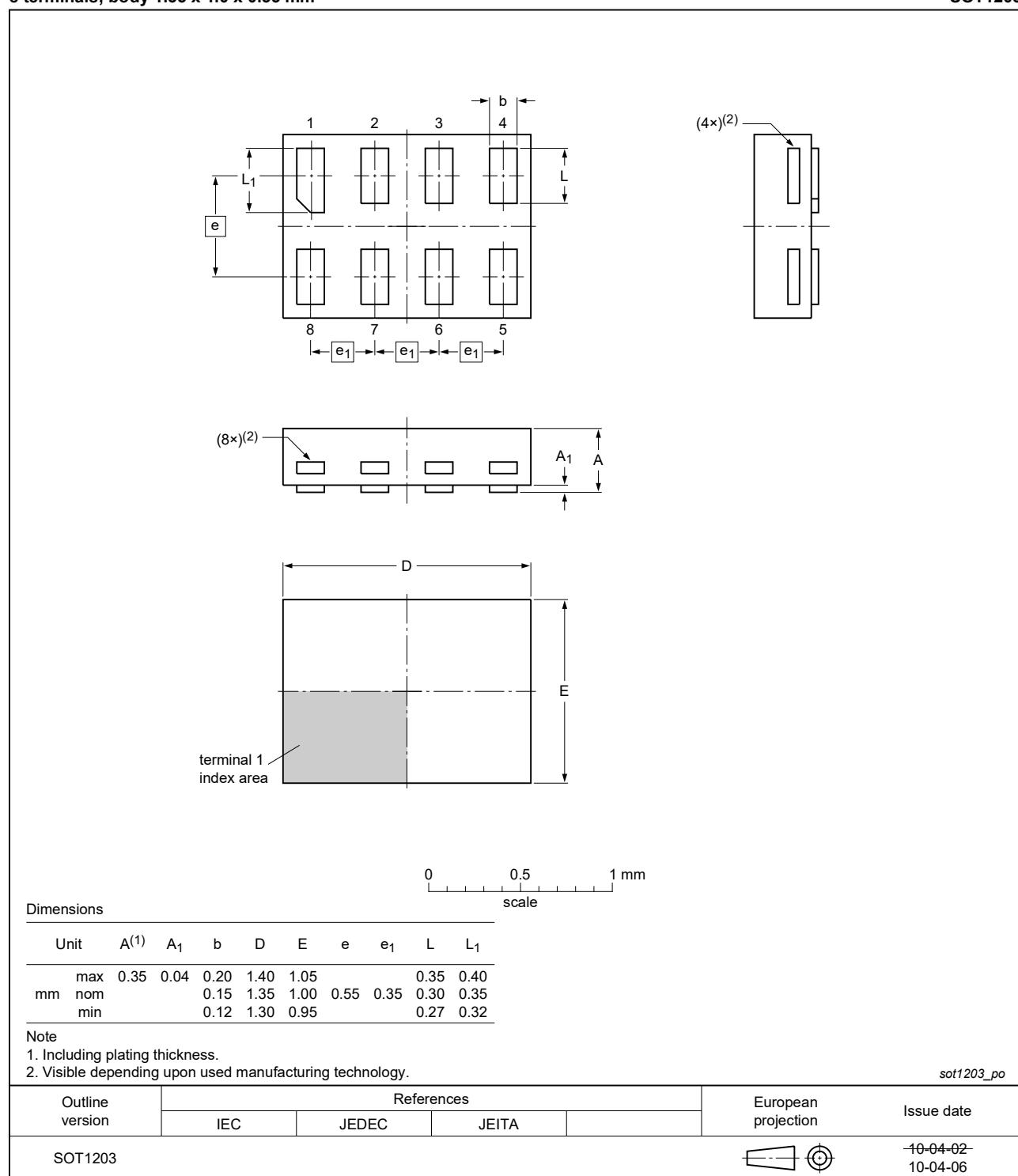


Fig. 11. Package outline SOT1203 (XSON8)

14. Abbreviations

Table 19. Abbreviations

Acronym	Description
ANSI	American National Standards Institute
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
ESDA	ElectroStatic Discharge Association
HBM	Human Body Model
JEDEC	Joint Electron Device Engineering Council

15. Revision history

Table 20. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74AVCH2T45 v.9.1	20240812	Product data sheet	-	74AVCH2T45 v.9
74AVCH2T45 v.9	20240625	Product data sheet	-	74AVCH2T45 v.8
Modifications:			<ul style="list-style-type: none"> Type number 74AVCH2T45GF (SOT1089/XSON8) removed. 	
74AVCH2T45 v.8	20221207	Product data sheet	-	74AVCH2T45 v.7
Modifications:			<ul style="list-style-type: none"> Section 2 updated. Table 5: Derating values for P_{tot} total power dissipation updated. 	
74AVCH2T45 v.7	20180220	Product data sheet	-	74AVCH2T45 v.6
Modifications:			<ul style="list-style-type: none"> The format of this data sheet has been redesigned to comply with the identity guidelines of Nexperia. Legal texts have been adapted to the new company name where appropriate. Removed type number 74AVCH2T45GD (SOT996-2/XSON8) 	
74AVCH2T45 v.6	20130402	Product data sheet	-	74AVCH2T45 v.5
Modifications:			<ul style="list-style-type: none"> For type number 74AVCH2T45GD XSON8U has changed to XSON8. 	
74AVCH2T45 v.5	20111214	Product data sheet	-	74AVCH2T45 v.4
Modifications:			<ul style="list-style-type: none"> Legal pages updated. 	
74AVCH2T45 v.4	20101124	Product data sheet	-	74AVCH2T45 v.3
74AVCH2T45 v.3	20090506	Product data sheet	-	74AVCH2T45 v.2
74AVCH2T45 v.2	20090203	Product data sheet	-	74AVCH2T45 v.1
74AVCH2T45 v.1	20070703	Product data sheet	-	-

16. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the internet at <https://www.nexperia.com>.

Definitions

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For sales office addresses, please send an email to: salesaddresses@nexperia.com

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